

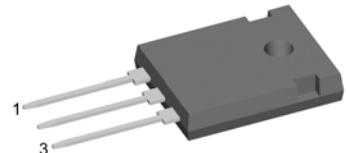
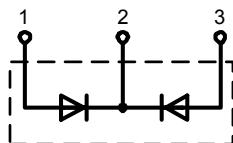
## HiPerFRED

High Performance Fast Recovery Diode  
Low Loss and Soft Recovery  
Common Cathode

**V<sub>RRM</sub> = 300 V**  
**I<sub>FAV</sub> = 2x 30 A**  
**t<sub>rr</sub> = 35 ns**

Part number (Marking on product)

**DPG 60 C 300HB**



### Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low I<sub>rm</sub>-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low I<sub>rm</sub> reduces:
  - Power dissipation within the diode
  - Turn-on loss in the commuting switch

### Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

### Package:

- TO-247AD
- Industry standard outline
  - Epoxy meets UL 94V-0
  - RoHS compliant

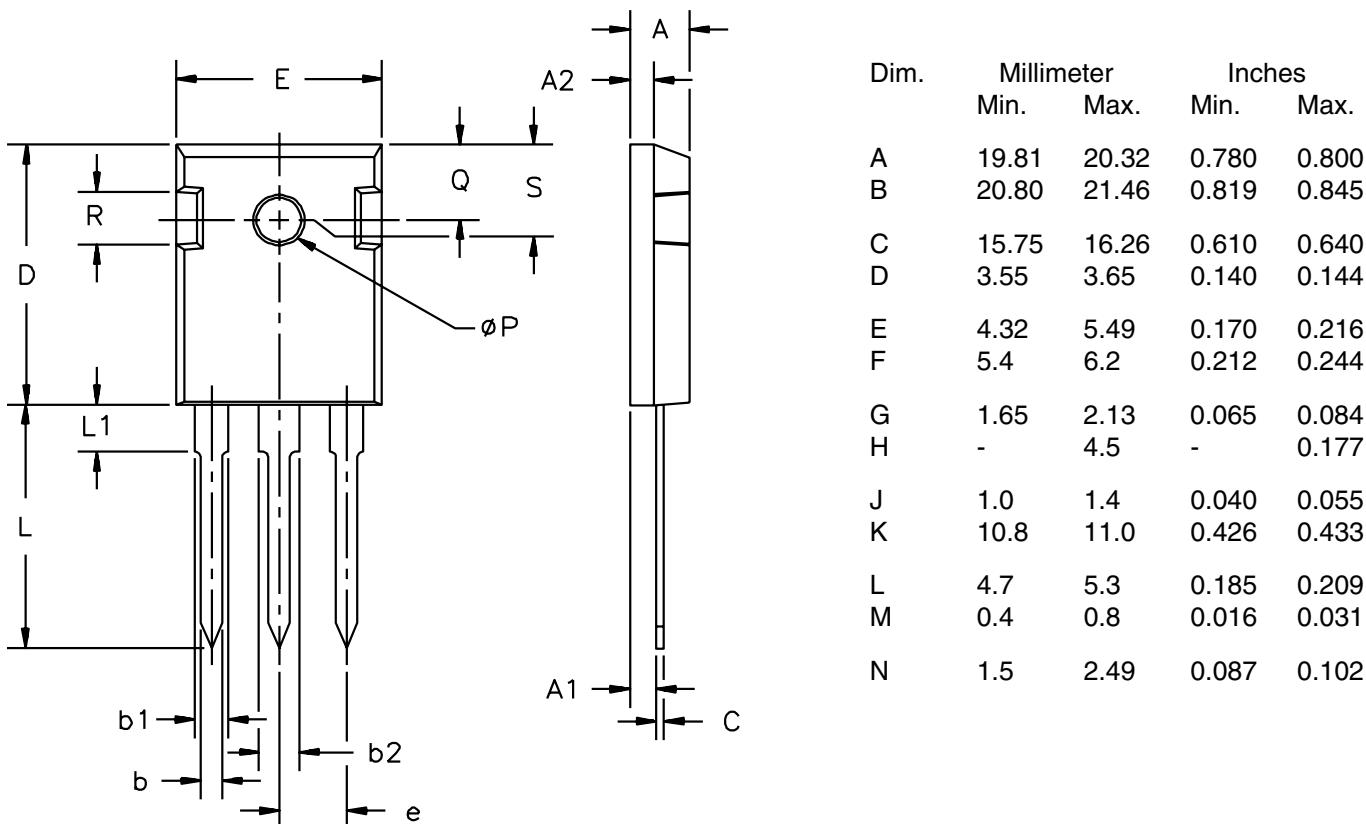
Ratings						
Symbol	Definition	Conditions	min.	typ.	max.	Unit
V <sub>RRM</sub>	max. repetitive reverse voltage	T <sub>vj</sub> = 25 °C			300	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 300 V      T <sub>vj</sub> = 25 °C V <sub>R</sub> = 300 V      T <sub>vj</sub> = 150 °C			1	µA
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 30 A      T <sub>vj</sub> = 25 °C I <sub>F</sub> = 60 A I <sub>F</sub> = 30 A      T <sub>vj</sub> = 150 °C I <sub>F</sub> = 60 A			1.34 1.63 1.06 1.39	V
I <sub>FAV</sub>	average forward current	rectangular, d = 0.5      T <sub>c</sub> = 135 °C			30	A
V <sub>F0</sub> r <sub>F</sub>	threshold voltage slope resistance } for power loss calculation only				0.70 10.5	V mΩ
R <sub>thJC</sub>	thermal resistance junction to case				0.95	K/W
T <sub>vj</sub>	virtual junction temperature		-55		175	°C
P <sub>tot</sub>	total power dissipation	T <sub>c</sub> = 25 °C			160	W
I <sub>FSM</sub>	max. forward surge current	t <sub>p</sub> = 10 ms (50 Hz), sine      T <sub>vj</sub> = 45 °C			300	A
I <sub>RM</sub>	max. reverse recovery current	I <sub>F</sub> = 30 A; -di <sub>F</sub> /dt = 200 A/µs	T <sub>vj</sub> = 25 °C T <sub>vj</sub> = 125 °C		3	A
t <sub>rr</sub>	reverse recovery time	V <sub>R</sub> = 100 V	T <sub>vj</sub> = 25 °C T <sub>vj</sub> = 125 °C	35		ns ns
C <sub>J</sub>	junction capacitance	V <sub>R</sub> = 150 V; f = 1 MHz	T <sub>vj</sub> = 25 °C		40	pF
E <sub>AS</sub>	non-repetitive avalanche energy	I <sub>AS</sub> = 9 A; L = 100 µH	T <sub>vj</sub> = 25 °C		4	mJ
I <sub>AR</sub>	repetitive avalanche current	V <sub>A</sub> = 1.5 · V <sub>R</sub> typ.; f = 10 kHz			0.9	A

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
$I_{RMS}$	RMS current	per pin*			50	A
$R_{thCH}$	thermal resistance case to heatsink			0.25		K/W
$M_D$	mounting torque		0.8		1.2	Nm
$F_c$	mounting force with clip		20		120	N
$T_{stg}$	storage temperature		-55		150	°C
<b>Weight</b>				6		g

\*  $I_{RMS}$  is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.

In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

### Outlines TO-247AD



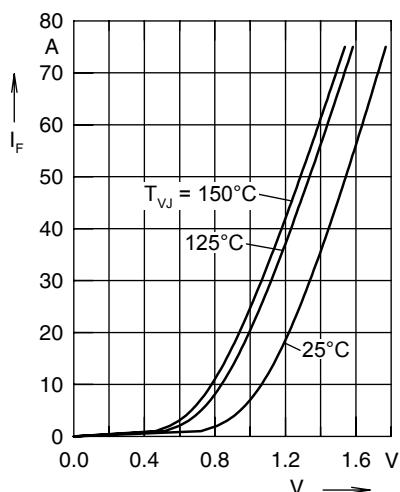
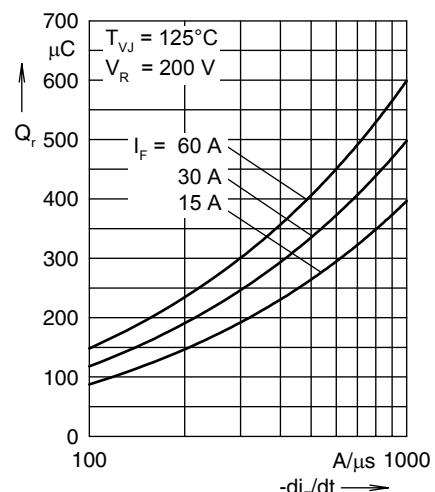
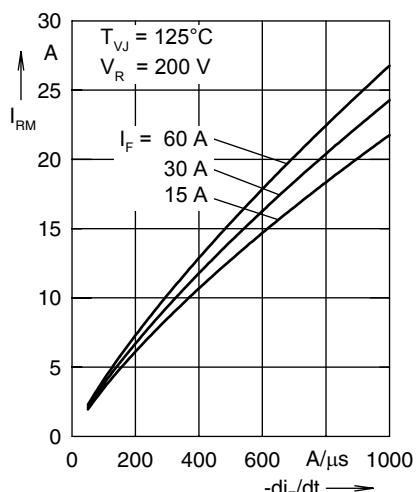
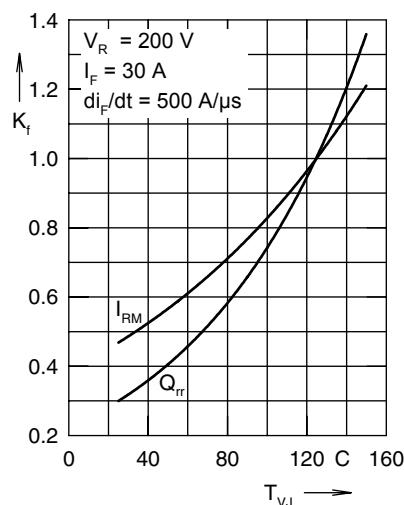
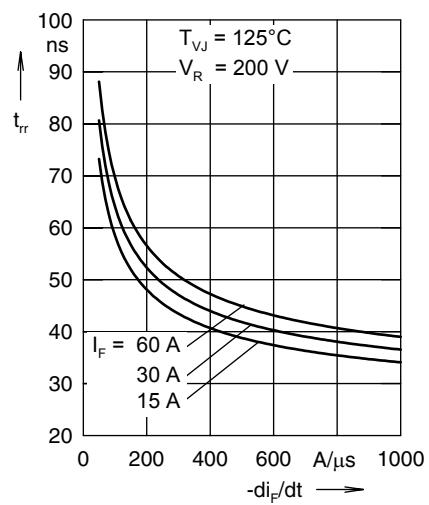
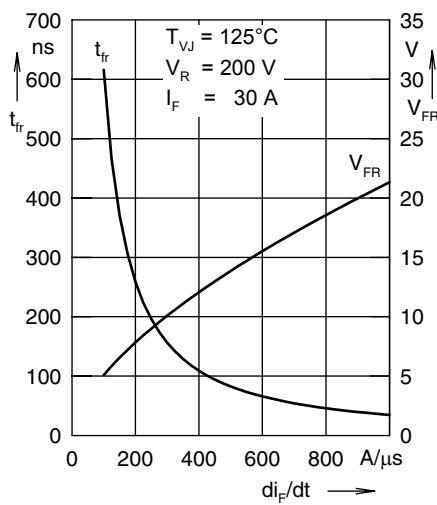
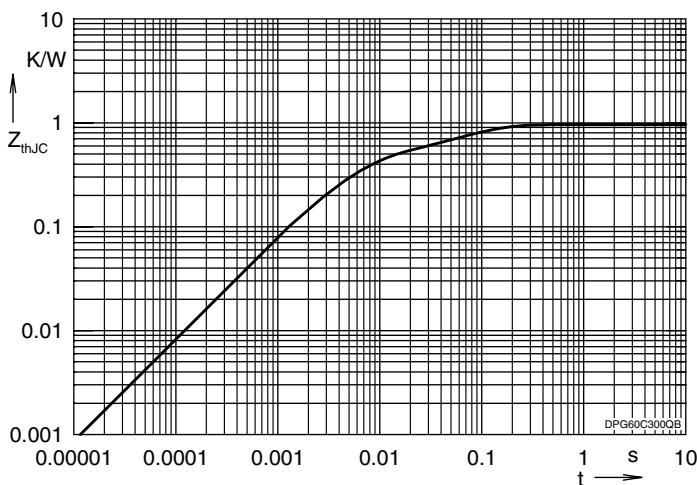
Fig. 1 Forward current  $I_F$  vs.  $V_F$ Fig. 2 Typ. reverse recovery charge  $Q_r$  versus  $-di_F/dt$ Fig. 3 Typ. peak reverse current  $I_{RM}$  versus  $-di_F/dt$ Fig. 4 Dynamic parameters  $Q_r$ ,  $I_{RM}$  versus  $T_{VJ}$ Fig. 5 Typ. recovery time  $t_{rr}$  vs.  $-di_F/dt$ Fig. 6 Typ. peak forward voltage  $V_{FR}$  and  $t_{fr}$  versus  $di_F/dt$ 

Fig. 7 Transient thermal impedance junction to case

IXYS reserves the right to change limits, conditions and dimensions.

\* Data according to IEC 60747 and per diode unless otherwise specified

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